

REINFORCED CHEMICAL MECHANICAL PLANARIZATION BELT

ABSTRACT OF THE DISCLOSURE

A method for fabricating a pad, a belt, or other polishing surface for use in
5 chemical mechanical planarization (CMP) system is provided. The method includes
providing a supporting mesh, a first polymeric material over the supporting mesh and a
second material such that the mesh is encased between the first polymeric material and
the second material. The first polymeric material, the supporting mesh, and the second
material are then bonded together.